

NOTES:

MATERIAL:

Insulator: High Temperature Thermoplastic, UL 94V-0.
Contact: Copper Alloy
Shell: STAINLESS

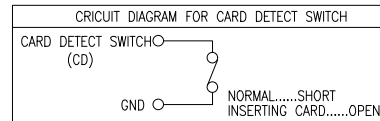
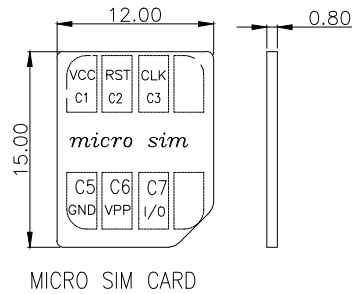
PLATING:

Contact: Plated 30u" Ni Overall ,Solder Area: Tin,Contact G/F
Shell: Plated 30u" Ni Overall
Plated G/F Selective Contact Area

Electrical:

Current Rating :0.5mA max.
Voltage Rating :50V DC MAX
Ambient Temperature Range :-20°C~+85°C
Storage Temperature Range :-40°C~+70°C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100mΩ max.
Insulation Resistance:1000MΩ min./250V DC
Dielectric Withstanding Voltage:500V AC
Mating Cycles:5,000 Insertions
Temperature: 260°C ±5°

SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O




■ CIRCUIT TRACE KEEP OUT AREA


■ SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

MANUFACTURE DWG	
UNLESS OTHERWISE SPECIFIED TOLERANCES	
DECIMALS:	ANGLES:


东莞市讯普电子科技有限公司
 DongGuan XunPu Electronics Co.,Ltd



TITLE:H1.35 7PIN MICRO SIM CARD PUSH PUSH
 PAR SMC-202S-ARP7
 DWN YAO 2017.05.25
 CHKD
 APVD
 SCALE:1:1 UNIT:MM
 SIZE:A4 SHEET:1F1 REV:A